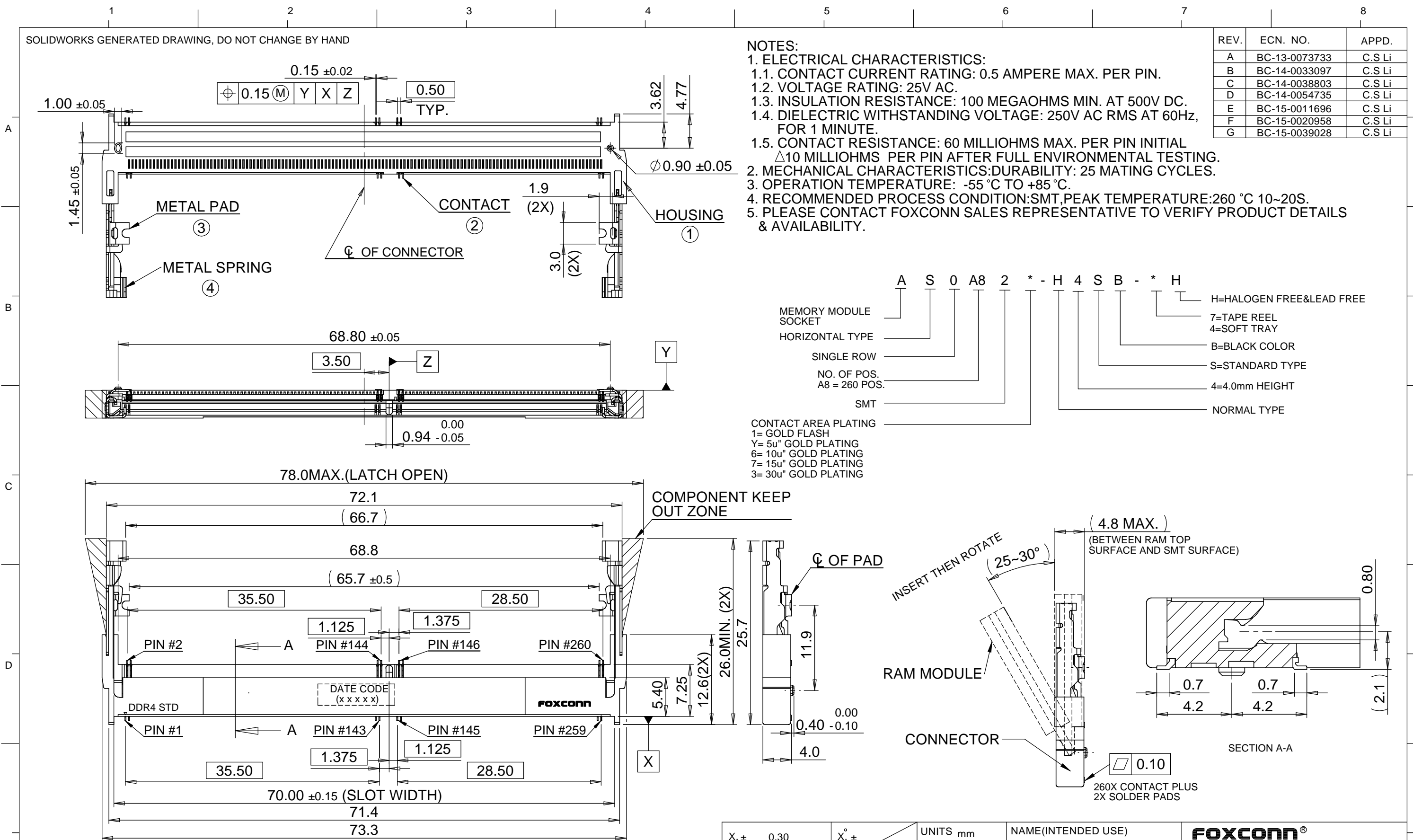


SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.
A	BC-13-0073733	C.S Li
B	BC-14-0033097	C.S Li
C	BC-14-0038803	C.S Li
D	BC-14-0054735	C.S Li
E	BC-15-0011696	C.S Li
F	BC-15-0020958	C.S Li
G	BC-15-0039028	C.S Li

- NOTES:**
- ELECTRICAL CHARACTERISTICS:**
    - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
    - VOLTAGE RATING: 25V AC.
    - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
    - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
    - CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL  
 $\Delta$ 10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
  - MECHANICAL CHARACTERISTICS:**DURABILITY: 25 MATING CYCLES.
  - OPERATION TEMPERATURE: -55 °C TO +85 °C.
  - RECOMMENDED PROCESS CONDITION:SMT,PEAK TEMPERATURE:260 °C 10~20S.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



**AS0A82\*-H4SB\*-H**

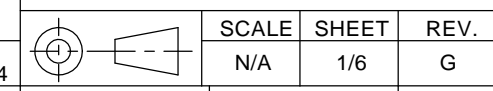
MEMORY MODULE SOCKET  
 HORIZONTAL TYPE  
 SINGLE ROW  
 NO. OF POS. A8 = 260 POS.  
 SMT

H=HALOGEN FREE&LEAD FREE  
 7=TAPE REEL  
 4=SOFT TRAY  
 B=BLACK COLOR  
 S=STANDARD TYPE  
 4=4.0mm HEIGHT  
 NORMAL TYPE

CONTACT AREA PLATING  
 1= GOLD FLASH  
 Y= 5u" GOLD PLATING  
 6= 10u" GOLD PLATING  
 7= 15u" GOLD PLATING  
 3= 30u" GOLD PLATING

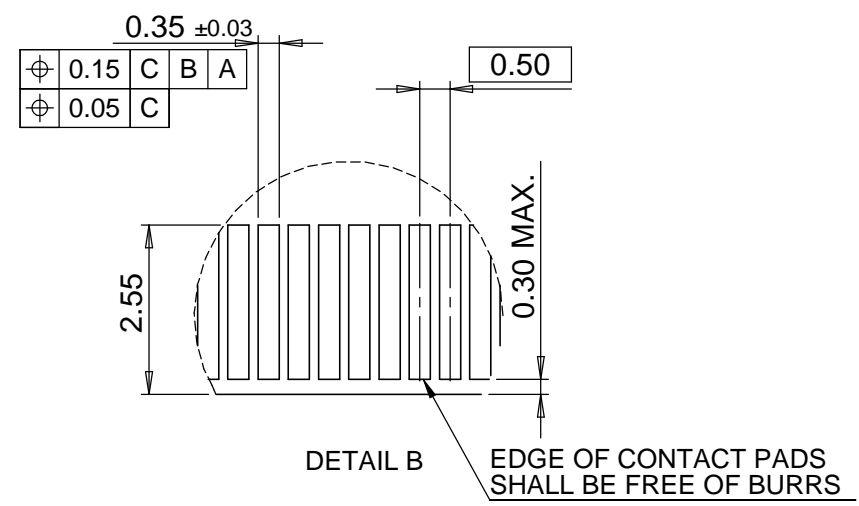
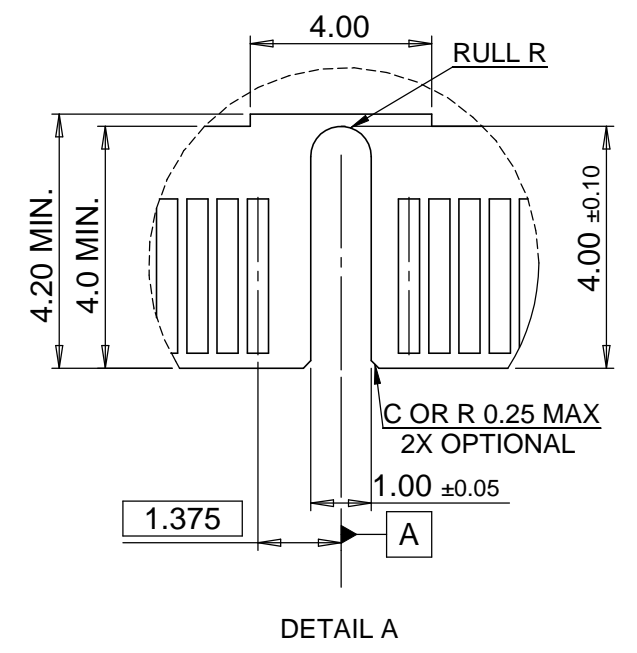
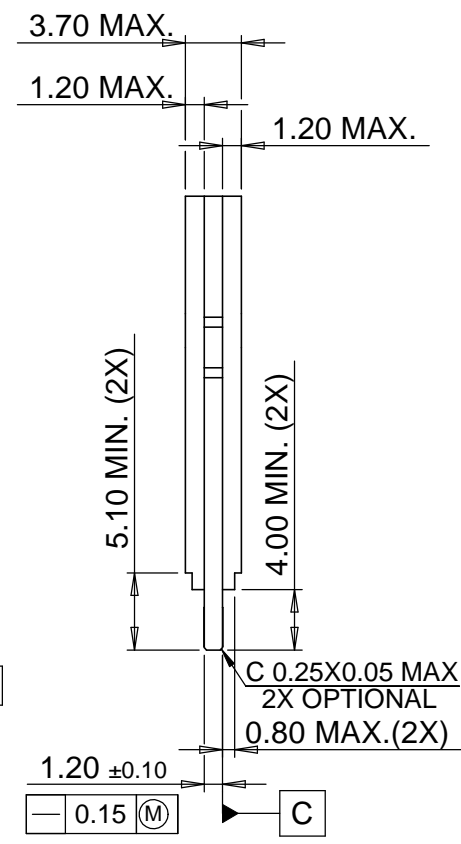
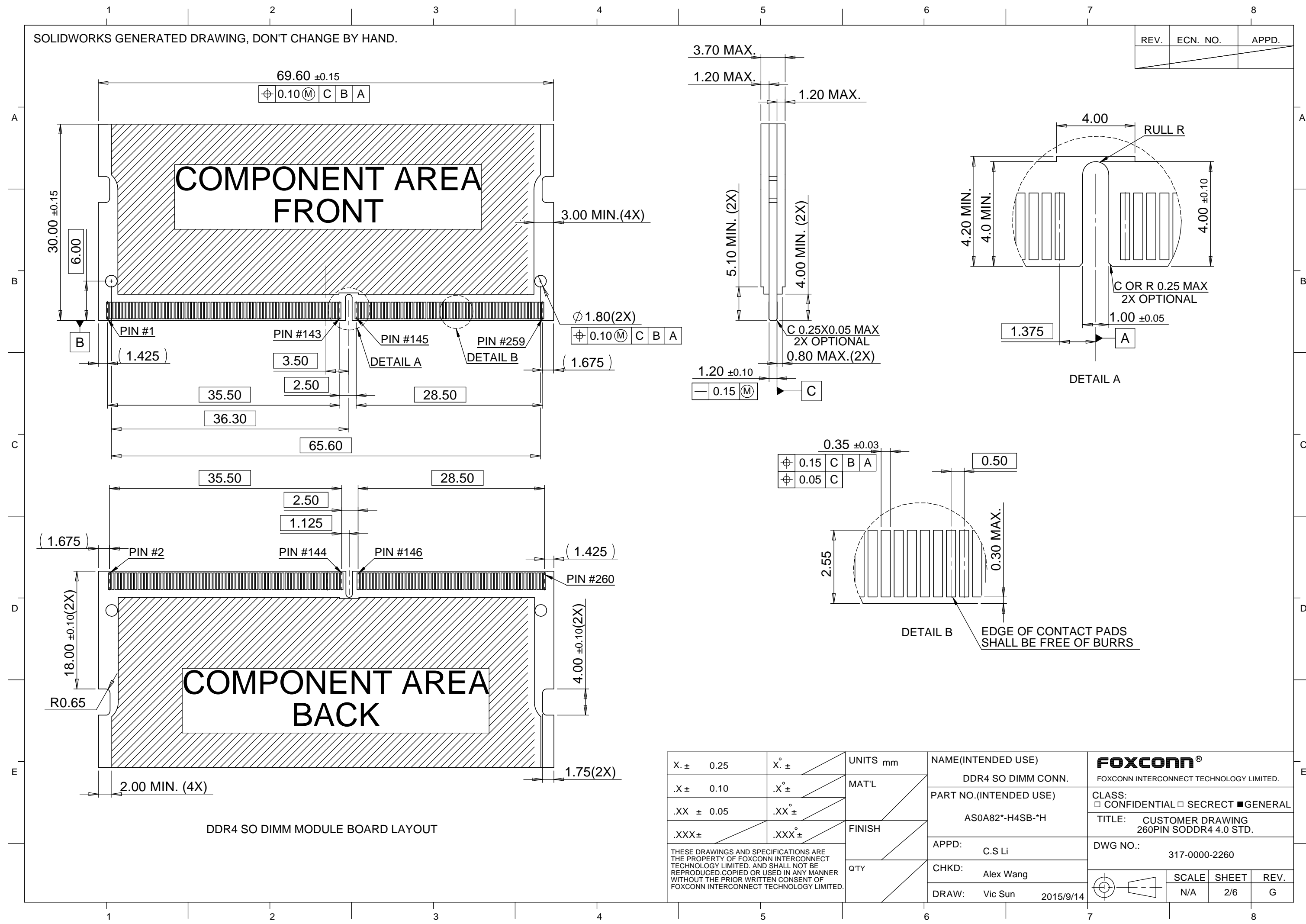
ITEM	DESCRIPTION	QTY	MATERIAL	TREATMENT
4	METAL SPRING	2	STAINLESS STEEL	ULTRASONIC CLEANING
3	METAL PAD	2	STAINLESS STEEL	10u" NICKEL UNDER PLATING 100u" MATTE TIN PLATING OVER SOLDER PAD AREA
2	CONTACT	260	PHOSPHOR BRONZE	50u" NICKEL UNDER PLATING GOLD FLASH PLATING AT TAIL GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA
1	HOUSING	1	LCP	UL94V-0, HALOGEN FREE, BLACK COLOR

UNIT	VALUE	TOLERANCE	UNITS	NAME (INTENDED USE)	FOXCONN®
X.±	0.30	X.°	mm	DDR4 SO DIMM CONN.	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X±	0.25	.X°	MAT'L	PART NO. (INTENDED USE)	CLASS: □ CONFIDENTIAL □ SECRET ■ GENERAL
.XX±	0.15	.XX°		AS0A82*-H4SB*-H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 STD.
.XXX±		.XXX°	FINISH	APPD: C.S Li	DWG NO.: 317-0000-2260
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				DRAW: Vic Sun 2015/9/14	SHEET: 1/6



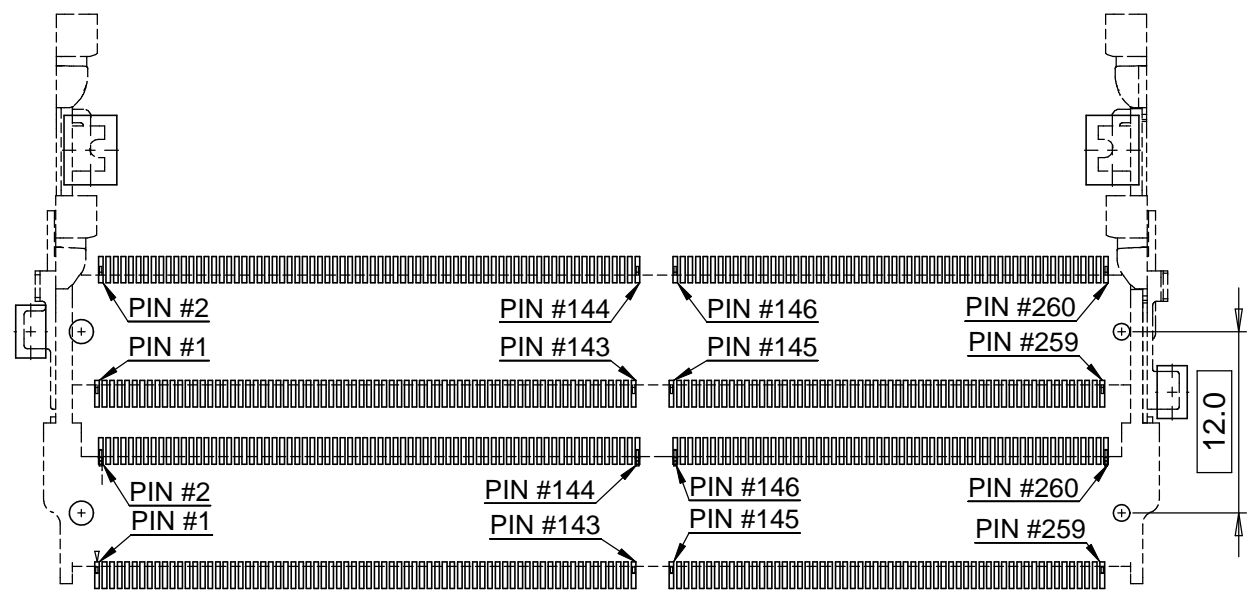
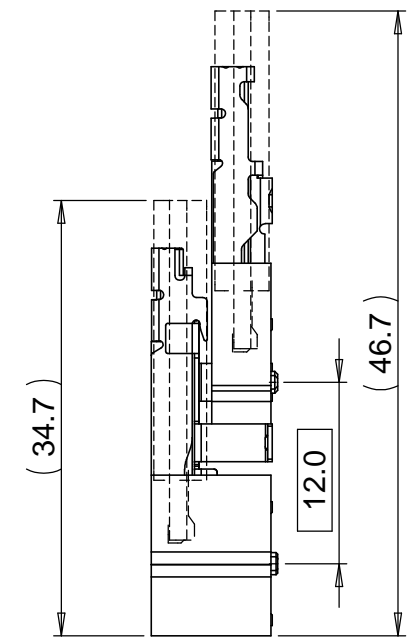
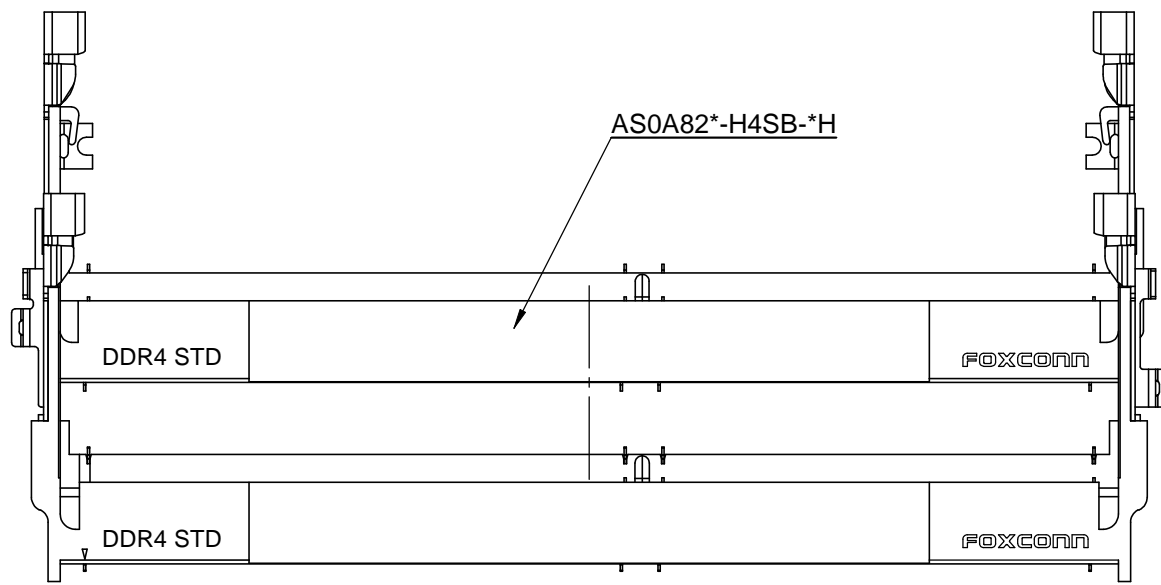
SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

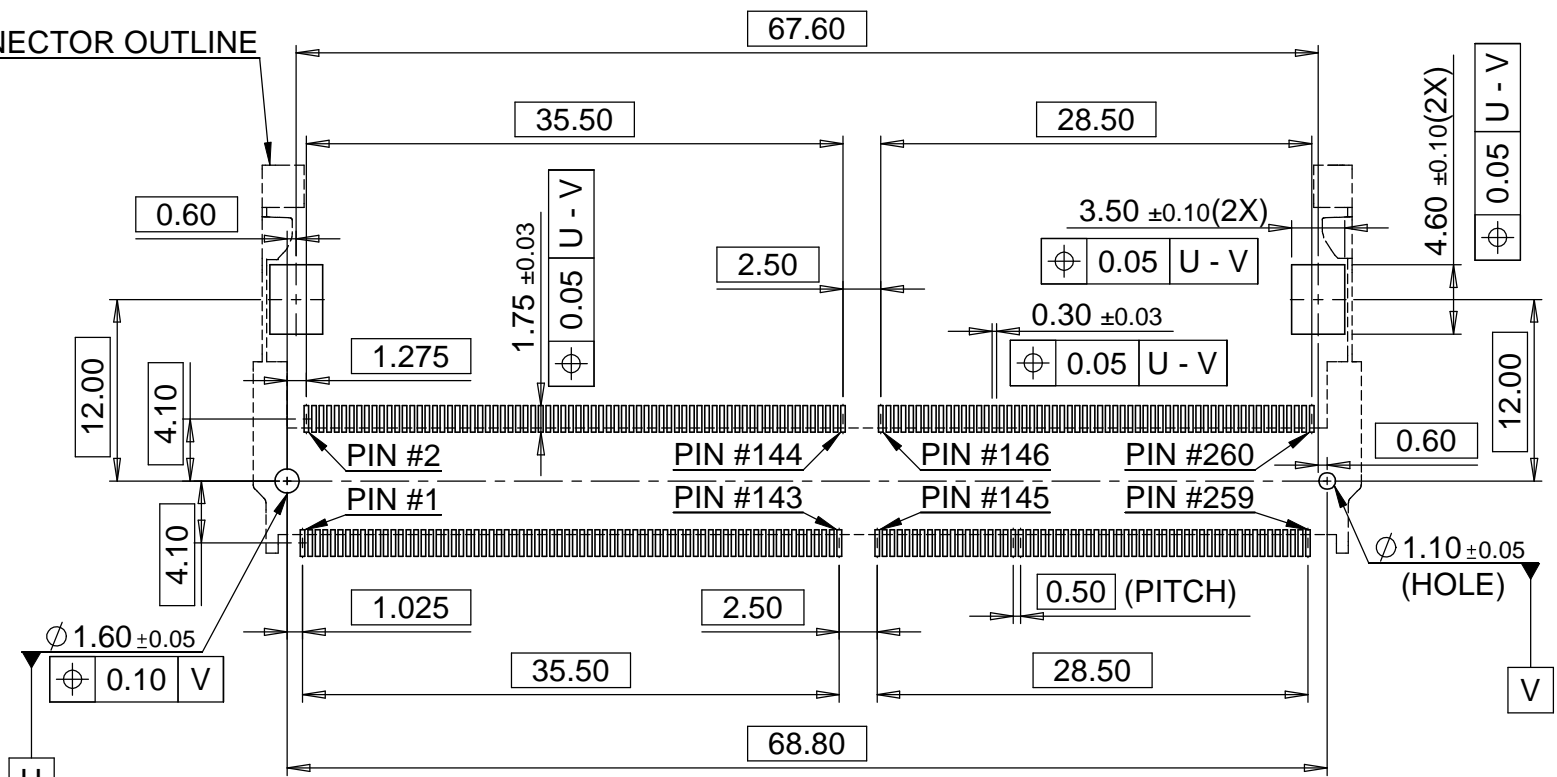


X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X °		DDR4 SO DIMM CONN.	
.XX ± 0.05	.XX °	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °	FINISH	AS0A82*-H4SB*-H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 STD.
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			CHKD: Alex Wang	SCALE SHEET REV.
			DRAW: Vic Sun 2015/9/14	N/A 2/6 G

REV.	ECN. NO.	APPD.



CONNECTOR OUTLINE



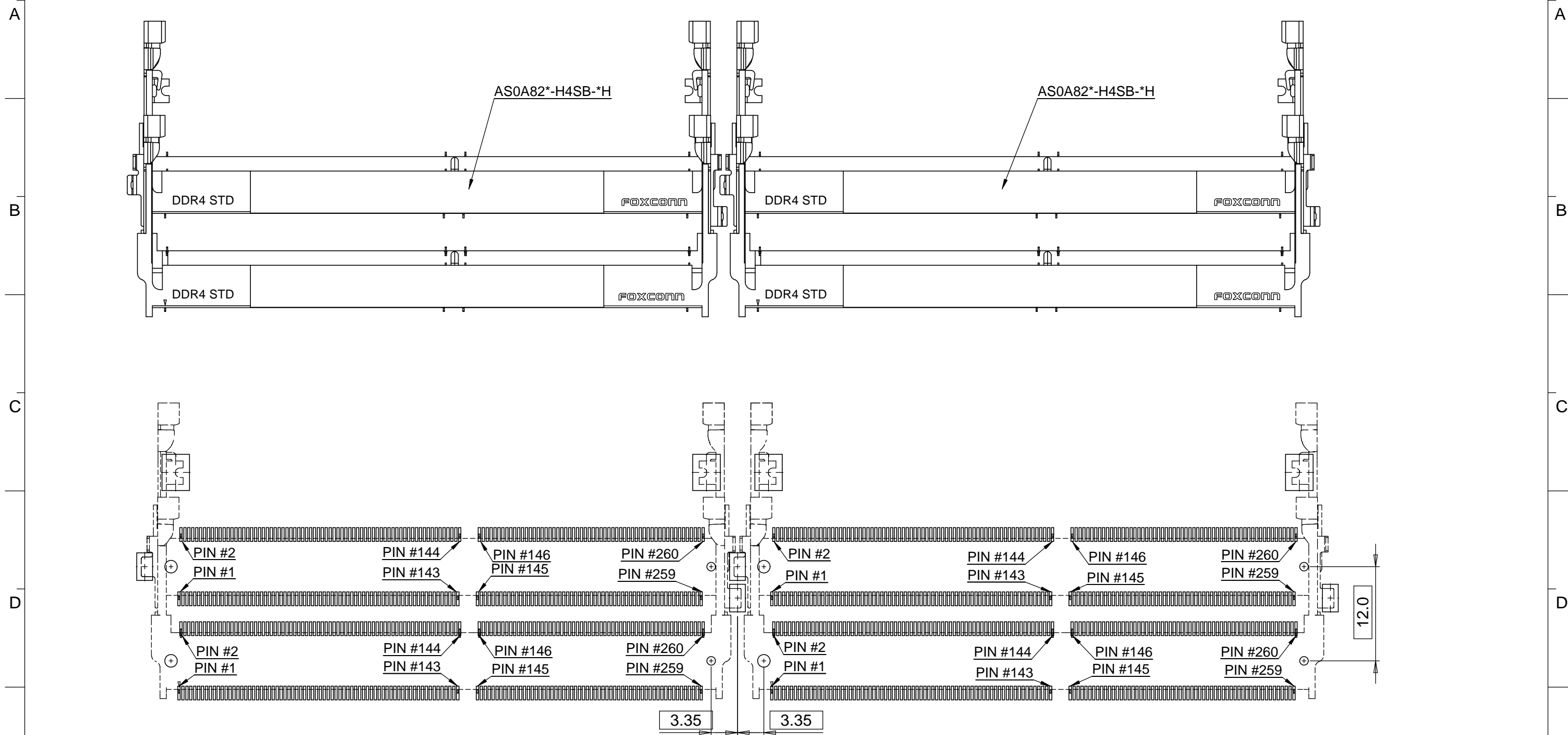
P.C.B. LAYOUT(RECOMMEND THICKNESS=1.40MM)

P.C.B. LAYOUT(STACKED ORIENTATION)

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±		DDR4 SO DIMM CONN.	
.XX ± 0.05	.XX° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A82*-H4SB-*H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 STD.
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.: 317-0000-2260
			CHKD: Alex Wang	SCALE SHEET REV. N/A 3/6 G
QTY			DRAW: Vic Sun 2015/9/14	

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

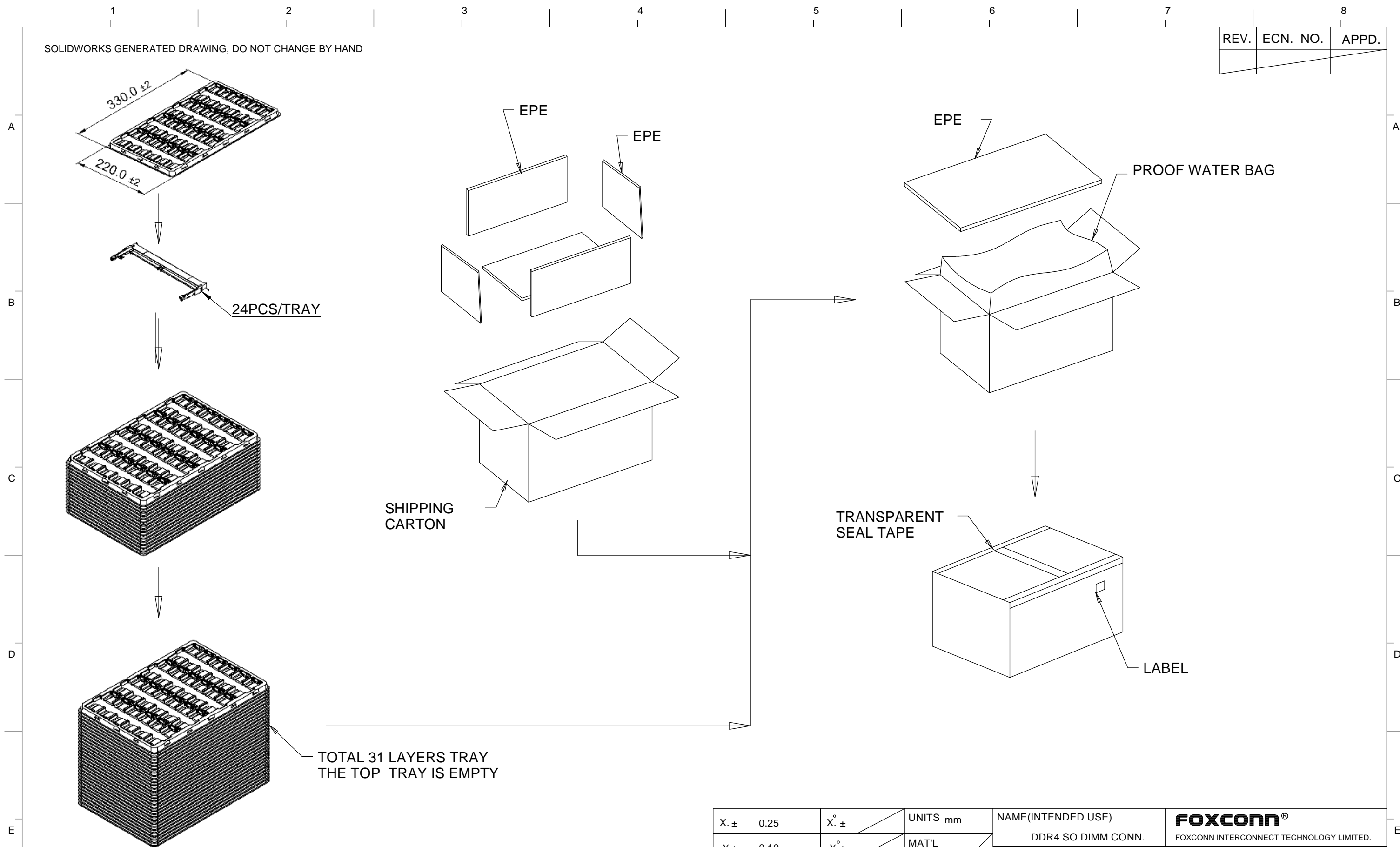


P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)

X. ± 0.25	X° ±	UNITS mm	NAME(INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		
.X ± 0.10	.X° ±				MAT'L	
.XX ± 0.05	.XX° ±	FINISH	PART NO.(INTENDED USE) AS0A82*-H4SB-*H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL		
.XXX ±	.XXX° ±			TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 STD.		
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			CHKD: Alex.Wang			
			DRAW: Vic Sun 2015/9/14			
				SCALE N/A	SHEET 4/6	REV. G

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.



TOTAL 31 LAYERS TRAY  
THE TOP TRAY IS EMPTY

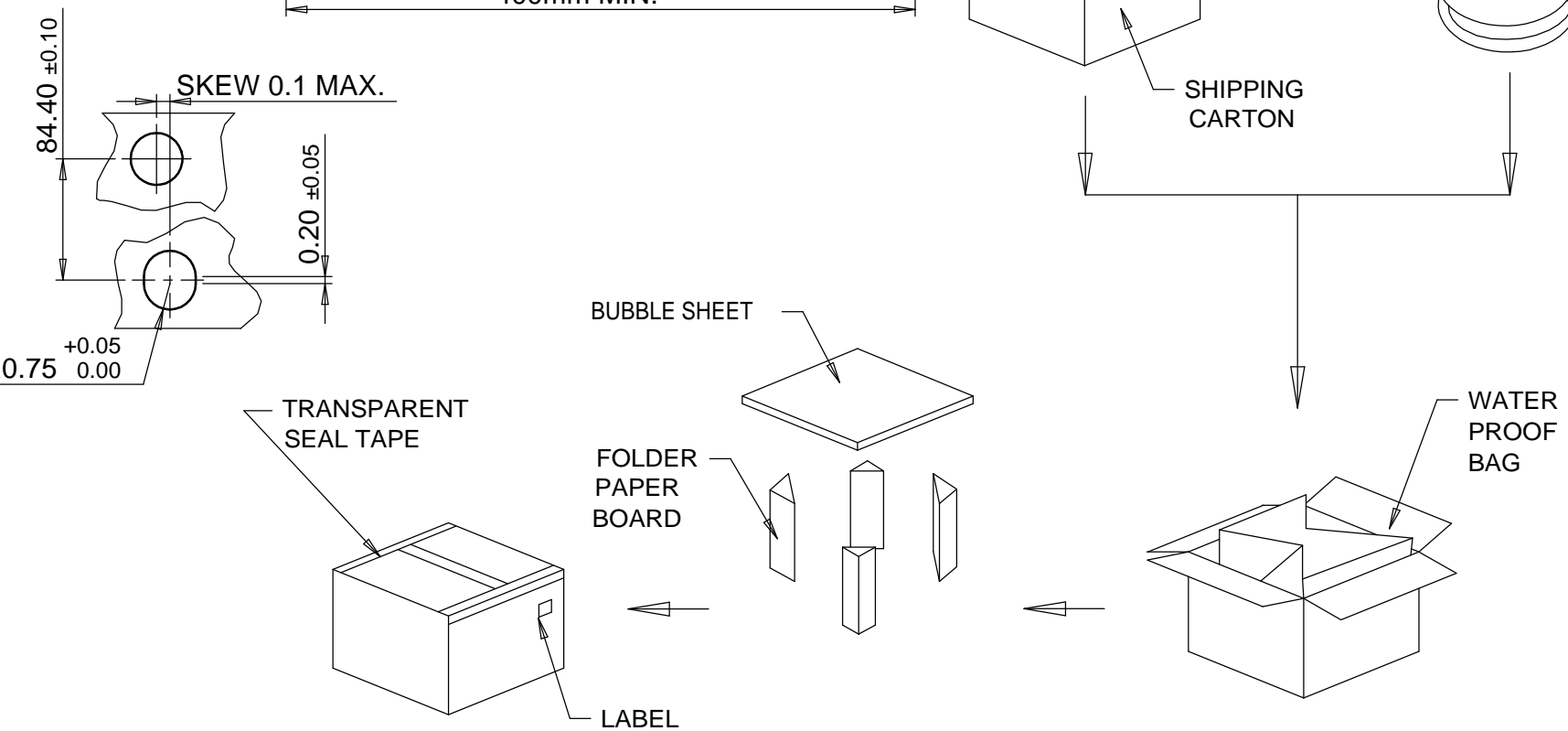
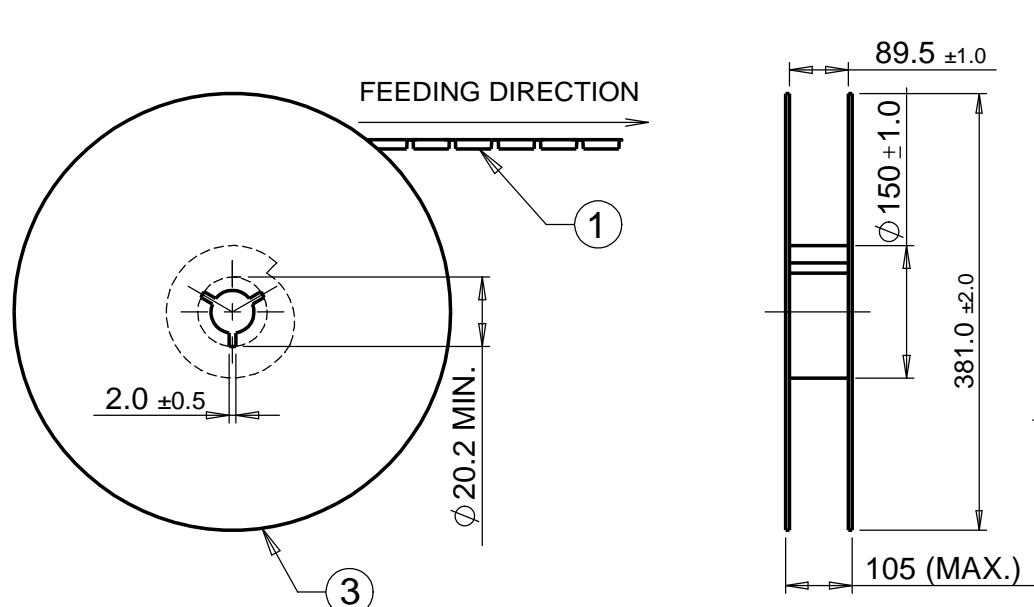
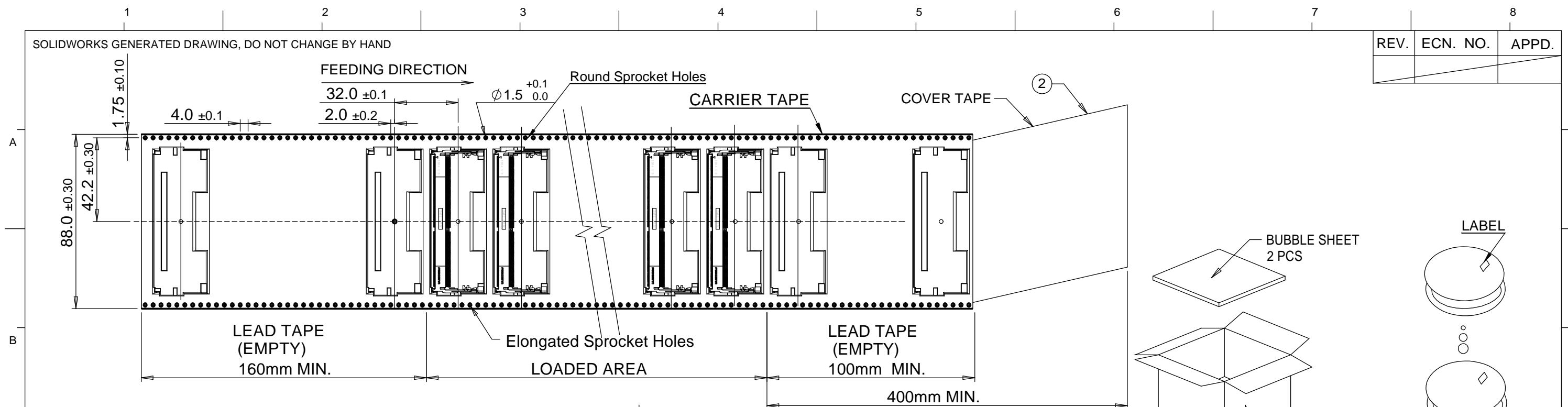
NOTES:  
1. PACKING CAPACITY : 24 PCS/TRAY, 30 TRAYS/BOX,  
TOTAL 720 PCS/BOX.

X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE) DDR4 SO DIMM CONN.	<b>FOXCONN</b> <sup>®</sup> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				
.X ± 0.10	.X °	MAT'L	PART NO. (INTENDED USE) AS0A82*-H4SB-*H					
.XX ± 0.05	.XX °	FINISH	APPD: C.S Li	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL				
.XXX ±	.XXX °	Q'TY	CHKD: Alex Wang	TITLE: CUSTOMER DRAWING 260PIN SODDR4 4.0 STD.				
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			<table border="1"> <tr> <td>SCALE</td> <td>SHEET</td> <td>REV.</td> </tr> <tr> <td>N/A</td> <td>5/6</td> <td>G</td> </tr> </table>			SCALE	SHEET	REV.
SCALE	SHEET	REV.						
N/A	5/6	G						

CONNECTOR P/N AS0A82\*-H4SB-4H

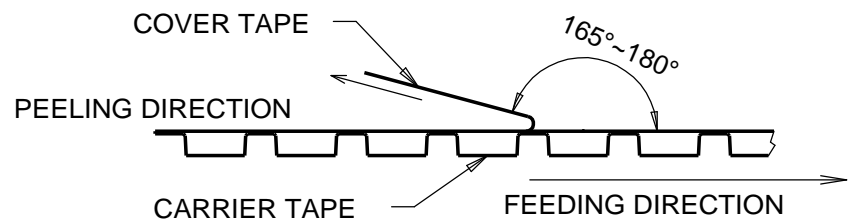
SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.



NOTES:

- 10 POKETS HOLE PITCH CUMULATIVE TOLERANCE  $\pm 0.20\text{mm}$ .
- COVER TAPE PEELING STRENGTH : 0.01 kgf MIN & 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 340 PCS/REEL, 3 REELS/BOX, TOTAL 1020 PCS/BOX.

3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X. °	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X °	MAT'L	DDR4 SO DIMM CONN.	
.XX ± 0.2	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		AS0A82*-H4SB-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 4.0 STD.
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			CHKD: Alex Wang	SCALE SHEET REV. N/A 6/6 G
			DRAW: Vic Sun 2015/9/14	

CONNECTOR P/N AS0A82\*-H4SB-7H